Hewlett Packard Enterprise

Product End-of-Life Disassembly Instructions

Product Category: *Storage*
Marketing Name / Model [List multiple models if applicable.]
HPE ProLiant DL380 G10 Plus Server for Cohesity

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	8
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		14
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

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Item Description	Notes	Quantity of items included in product
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx driver	T15
Phillips screwdriver	#2
Flathead screwdriver	Medium
Socket screwdriver	5 mm / 8 mm

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove top cover of systems by hood latch.
2. Remove Fan cage module, Air baffle and Riser cage from system.
3. Remove lithium battery from the system by medium flat head screw driver.
4. Remove Mega-cell HSTNS-BB05 from the system
5. Use Torx driver with T15 to unlock screws and remove bracket with PCA from LFF system \ remove HDD cage with PCA from SFF system.
6. Remove the Power supply(s) from system.
7. Use Torx driver with T15 to unlock thumbscrew and remove the System board with tray from system.
8. Riser cage : Use Torx driver with T15 to unlock screws and Remove the riser card (PCA)
9. bracket with PCA : Use Torx driver with T15 to unlock screws and remove HDD BP (PCA) from bracket [LFF system]
   HDD cage with PCA : Use Torx driver with T15 to unlock screws and remove HDD BP (PCA) from HDD cage [SFF system]
10. System board with tray : Use Torx driver with T15, 5 mm socket screwdriver and 8 mm socket screwdriver to unlock screws to remove System board (PCA) from tray.
11. Power supply(s) : Remove Capacitors > 2.5CM of the power supply(s) from the system. With #2 Philips screw driver remove the screws securing the top cover and the heatsinks in the P/S then locate the capacitors and pry from the PCB with a medium flat head screw driver and dispose of properly.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

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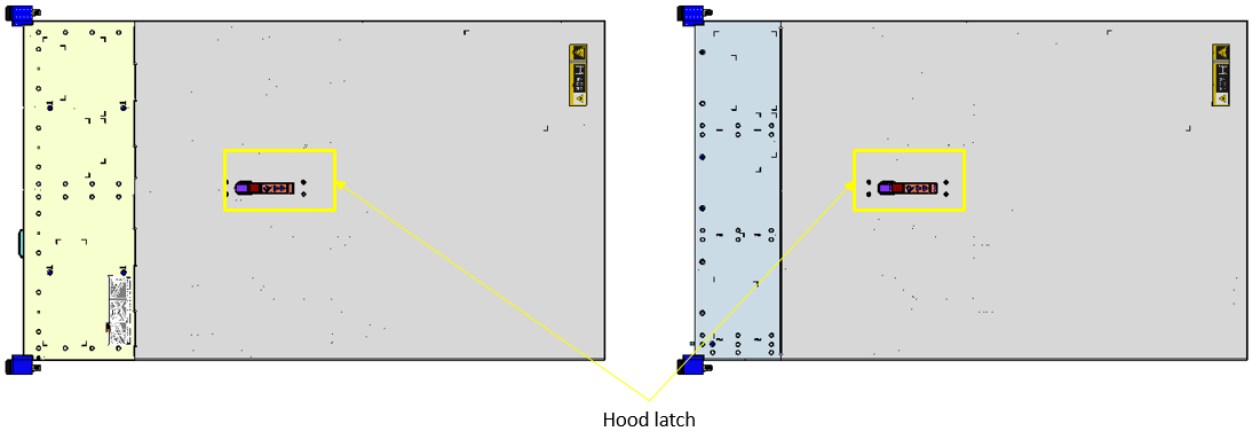
1. Remove top cover of systems by hood latch.

LFF system

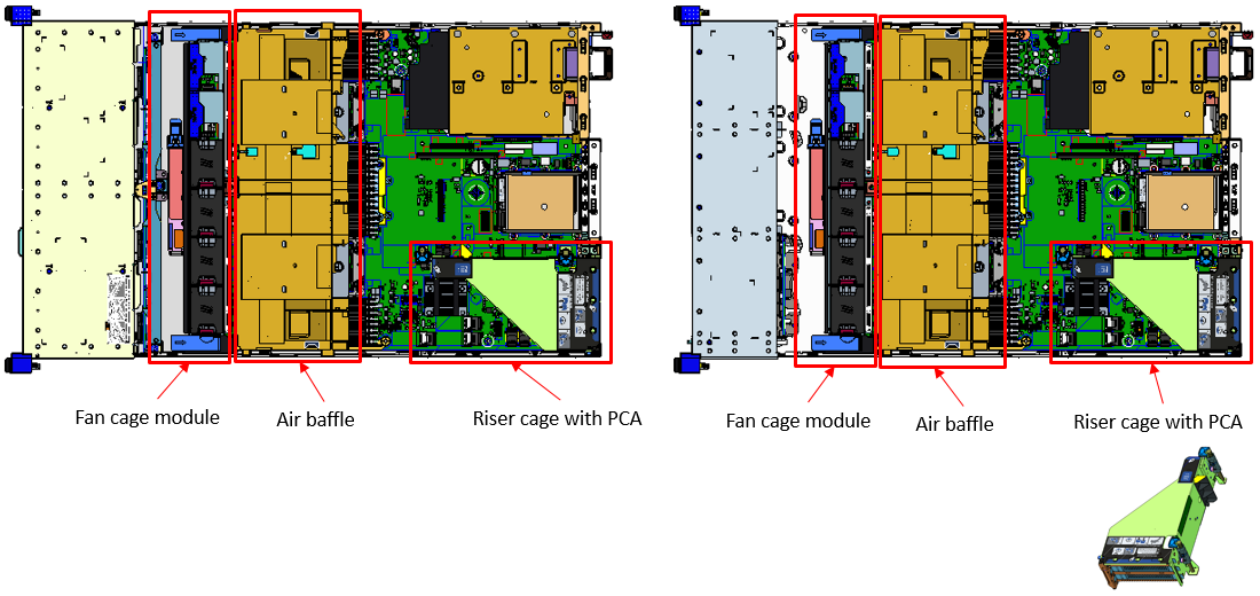
SFF system



2. Remove Fan cage module, Air baffle and Riser cage from system.

LFF system

SFF system



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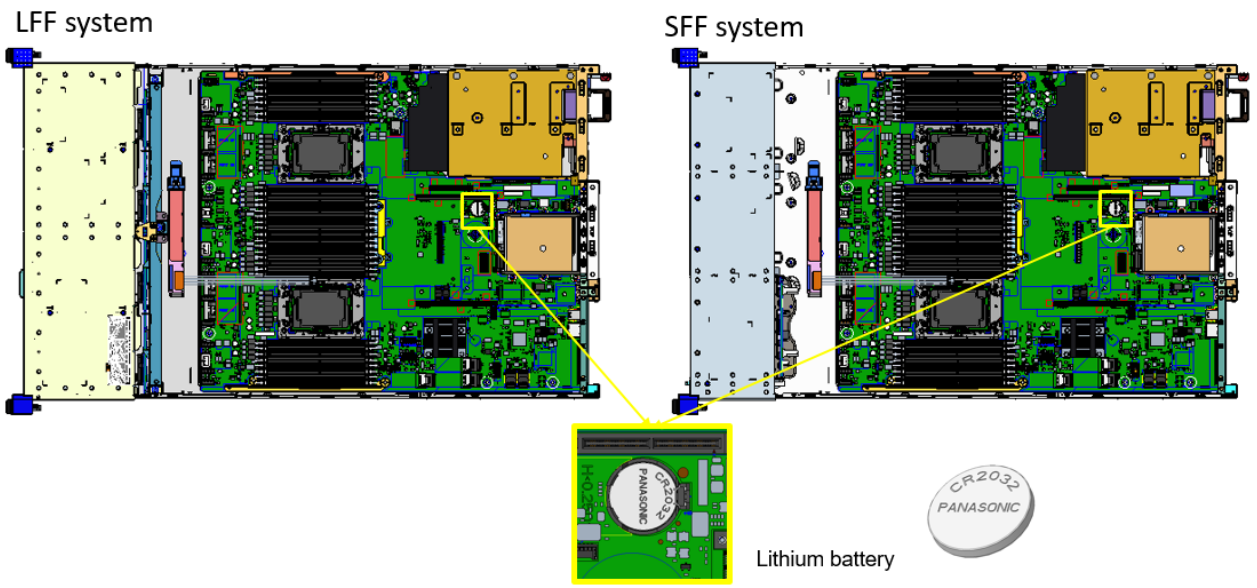
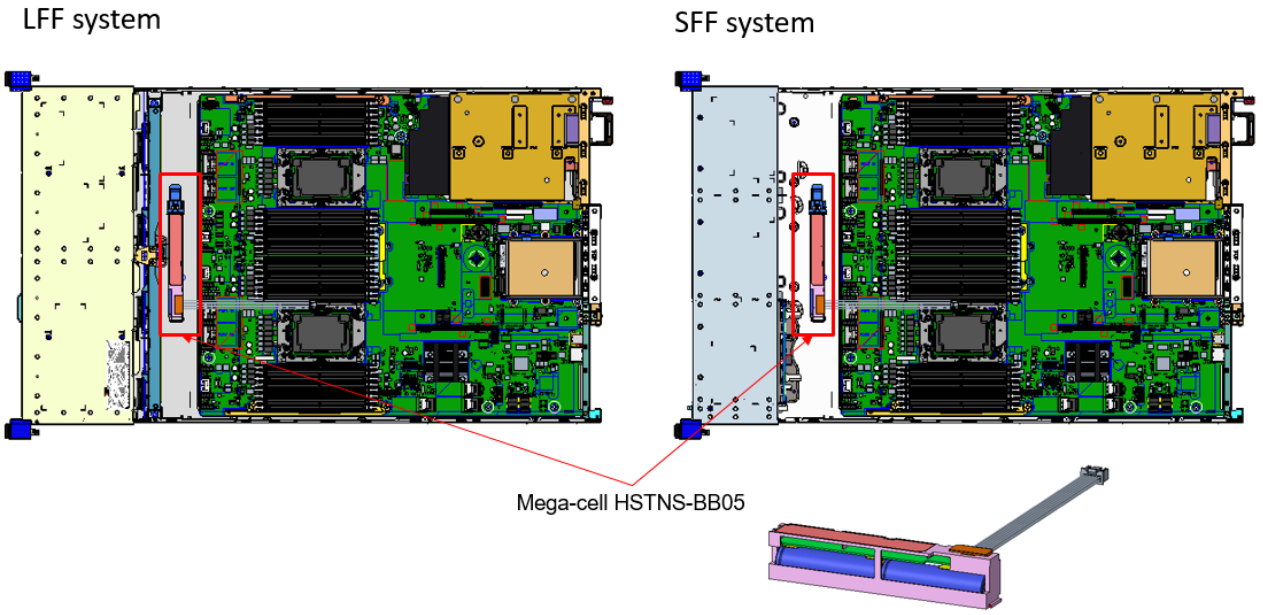
3. Remove lithium battery from the system by medium flat head screw driver.



4. Remove Mega-cell HSTNS-BB05 from the system



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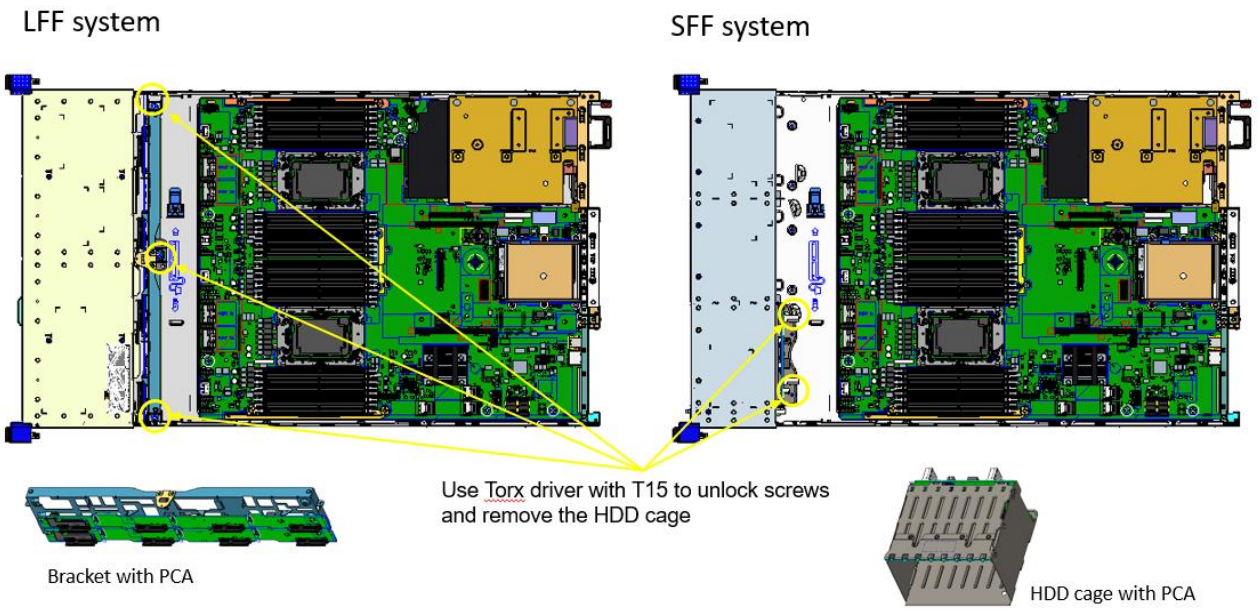
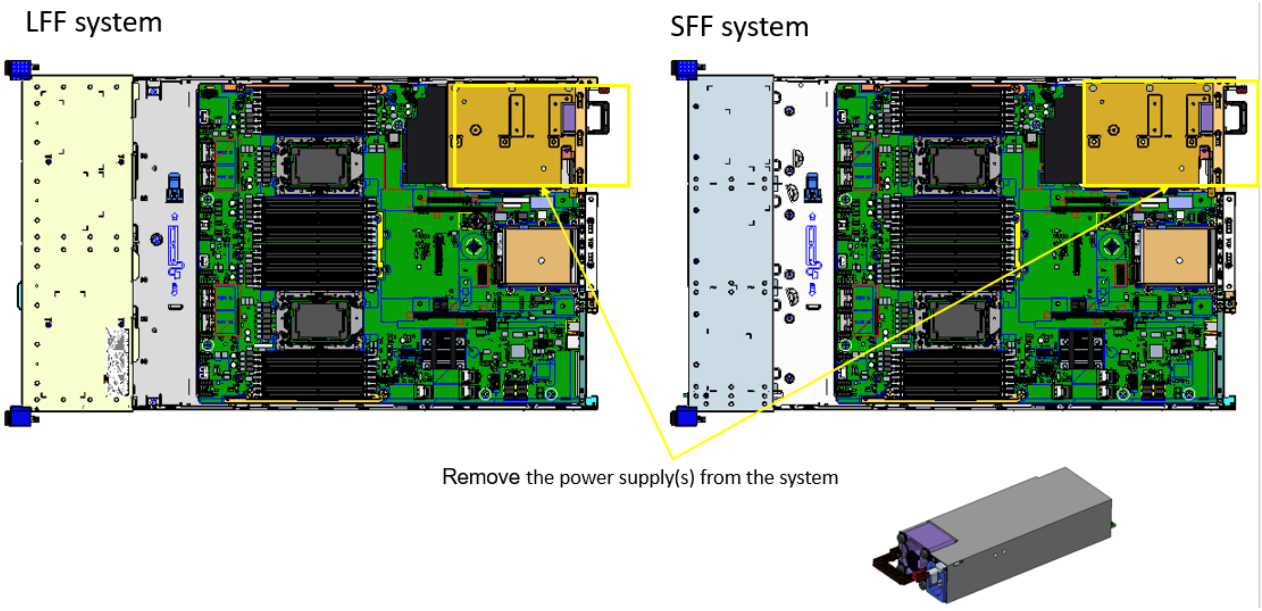
5_a. Use Torx driver with T15 to unlock screws

5_b. Remove bracket with PCA from LFF system \ Remove HDD cage with PCA from SFF system.



6. Remove the power supply(s) from system.



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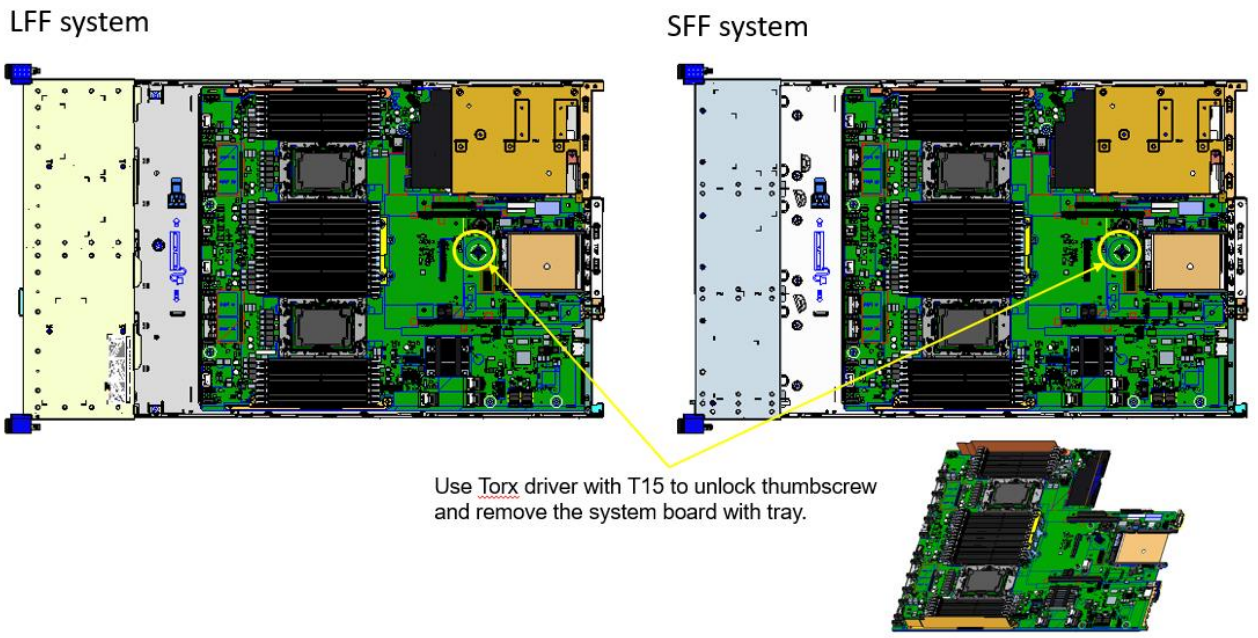
7_a. Use Torx driver with T15 to unlock thumbscrew.

7_b. Remove the system board with tray from system.



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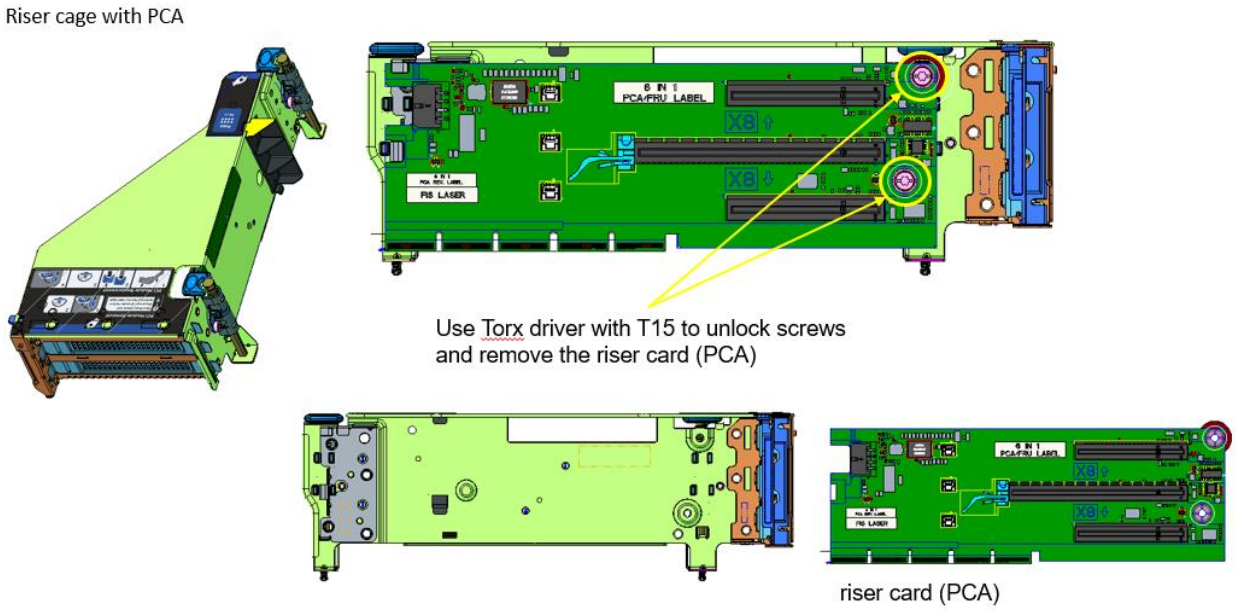
8_a. Use Torx driver with T15 to unlock screws.

8_b. Remove the riser card (PCA)



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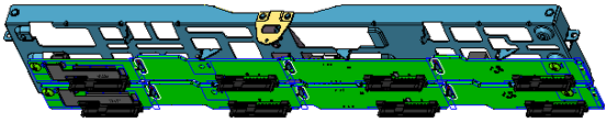
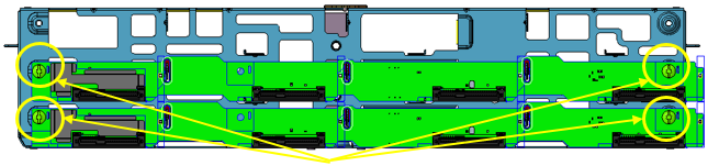
9_a. Use Torx driver with T15 to unlock screws.

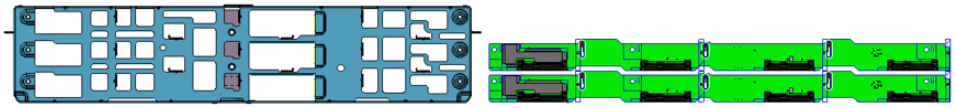
9_b. Remove HDD BP (PCA) from bracket [LFF system] \ Remove HDD BP (PCA) from HDD cage [SFF system].



Bracket with PCA

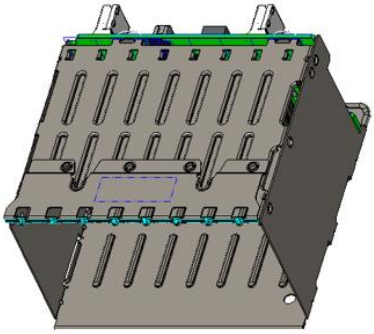


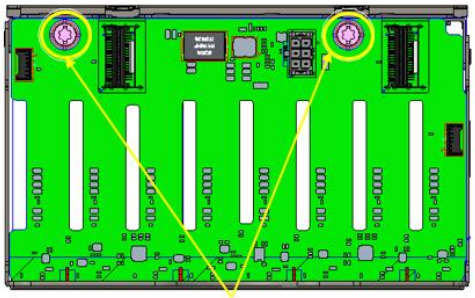
Use Torx driver with T15 to unlock screws
and remove the HDD BP (PCA)



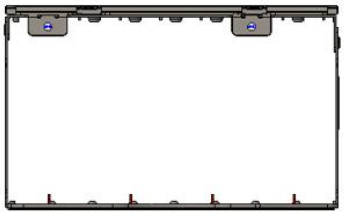
HDD BP (PCA)

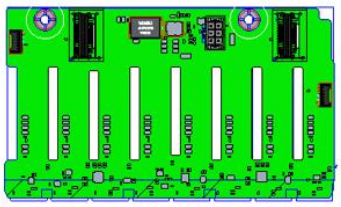
HDD cage with PCA





Use Torx driver with T15 to unlock screws
and remove the HDD BP (PCA)





HDD BP (PCA)

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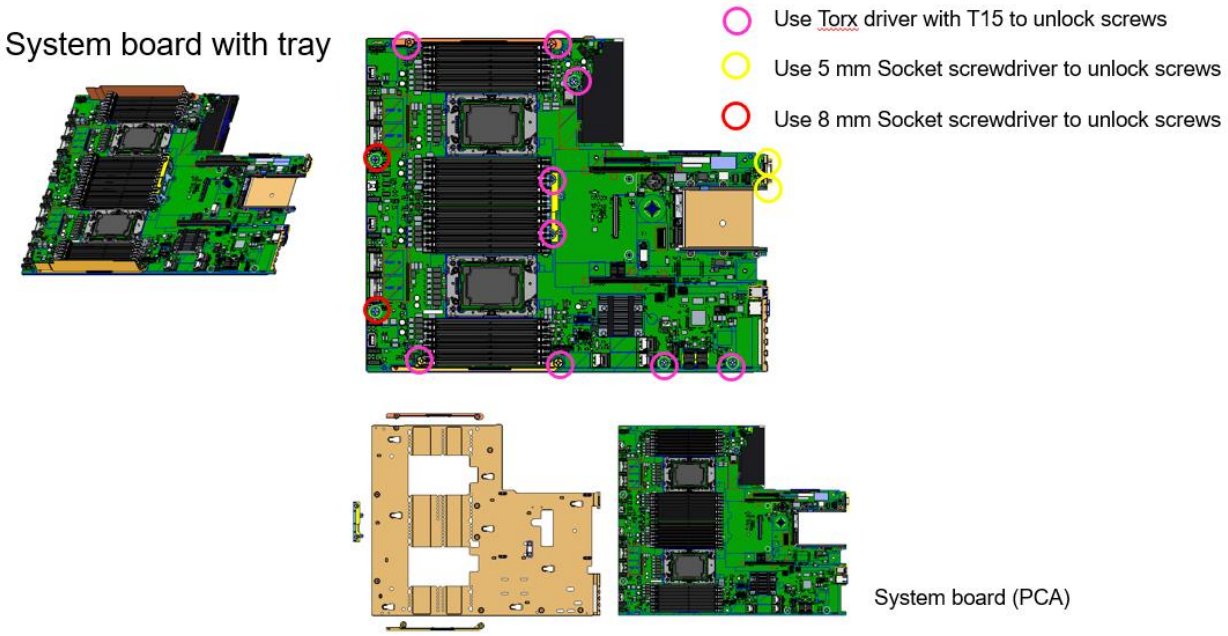
10_a. Use Torx driver with T15, 5 mm socket screwdriver and 8 mm socket screwdriver to unlock screws.

10_b. Remove System board (PCA) from tray.



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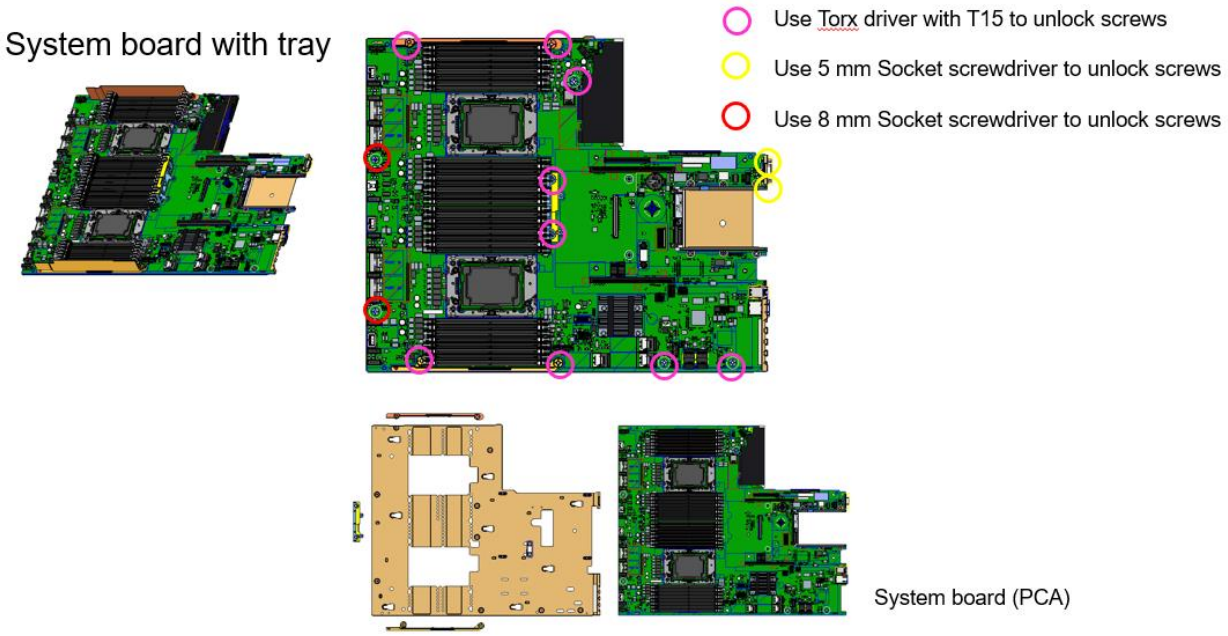
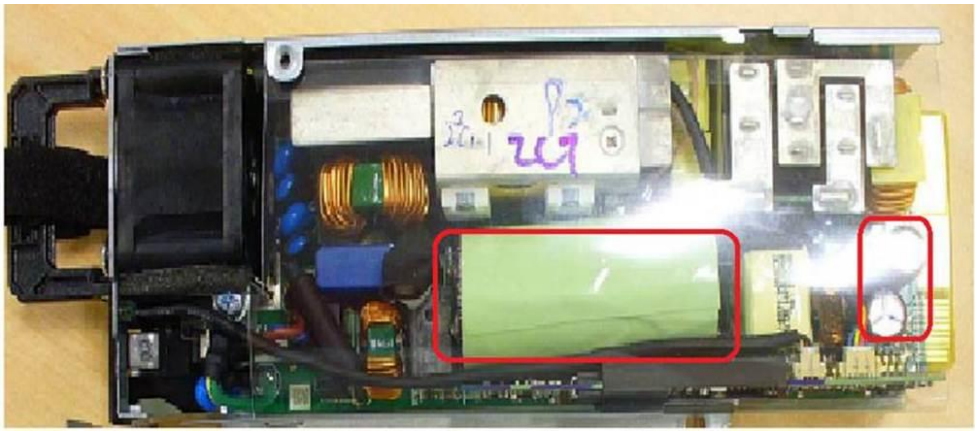
10_a. Use Torx driver with T15, 5 mm socket screwdriver and 8 mm socket screwdriver to unlock screws.

10_b. Remove System board (PCA) from tray.



Remove Electrolytic Capacitors (C801: 25mm*55mm and C237, C238, C241:10mm*25mm) from power supply HSTNS-PD40, HSTNS-PD40-1.



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Remove Electrolytic Capacitor(C102: 25mm*25mm) from HSTNS-PL40, HSTNS-PL40-1

Remove Electrolytic Capacitor (BC1: 25mm*60 mm and C106/C107/C108 10mm*25mm) from power supply HSTNS-PC40, HSTNS-PC40-1.

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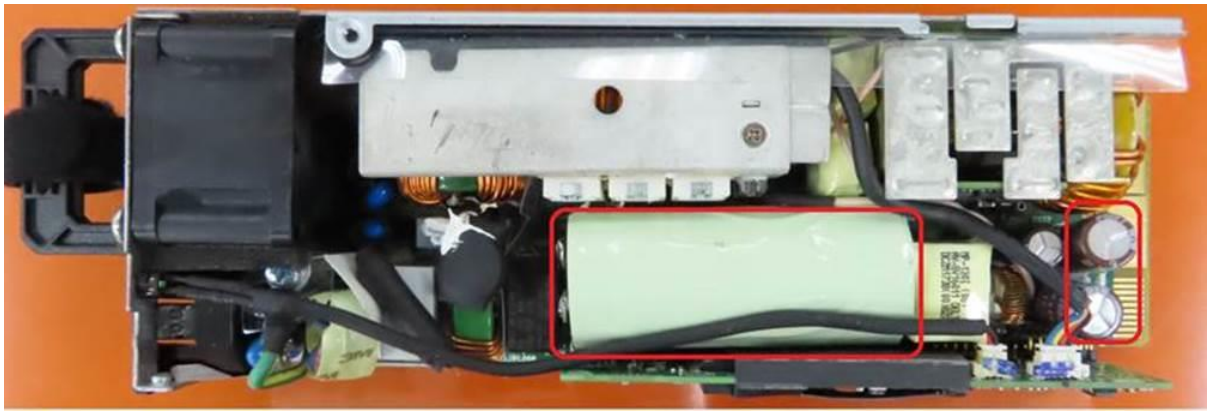
Remove Electrolytic Capacitor (C801:25mm*60mm and C237/C238/C241:10mm*25) from power supply HSTNS-PD41, HSTNS-PD41-1.



Remove Electrolytic Capacitor (C102: 30mm*30mm) from power supply HSTNS-PL41, HSTNS-PL41-1.

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Remove Electrolytic Capacitor (BC1: 25mm*60 mm and C106/C107/C108: 10mm*25mm) from power supply HSTNS-PC41, HSTNS-PC41-1.

Remove Electrolytic Capacitor (C801: 25mm*60mm and C212/C233/C238: 10mm*25mm) from power supply HSTNS-PD44, HSTNS-PD44-1.

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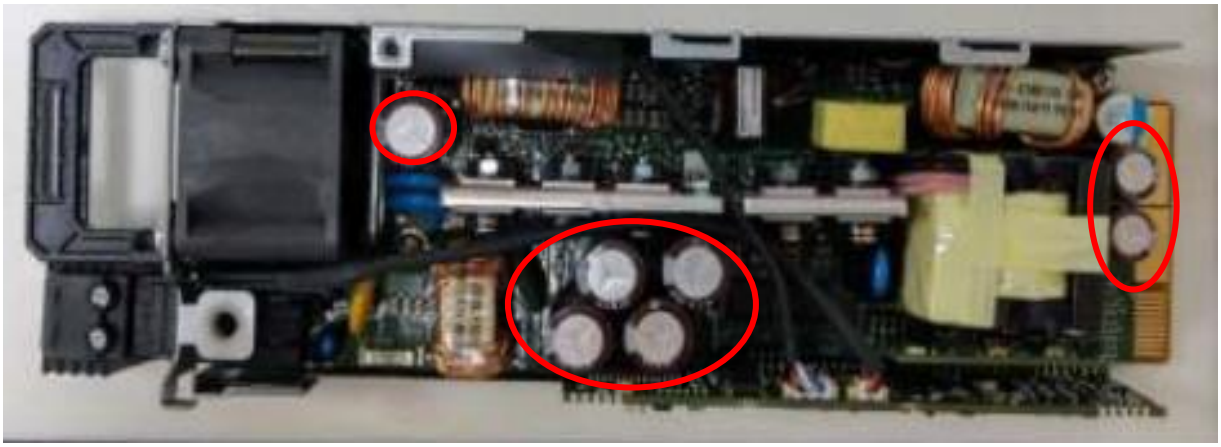
Remove Electrolytic Capacitor (C102: 30mm*30mm) from power supply HSTNS-PL45, HSTNS-PL45-1.

Remove Electrolytic Capacitor (C101,C105,C106,C114,C115: 8mm*20mm) from power supply HSTNS-PL46-1.



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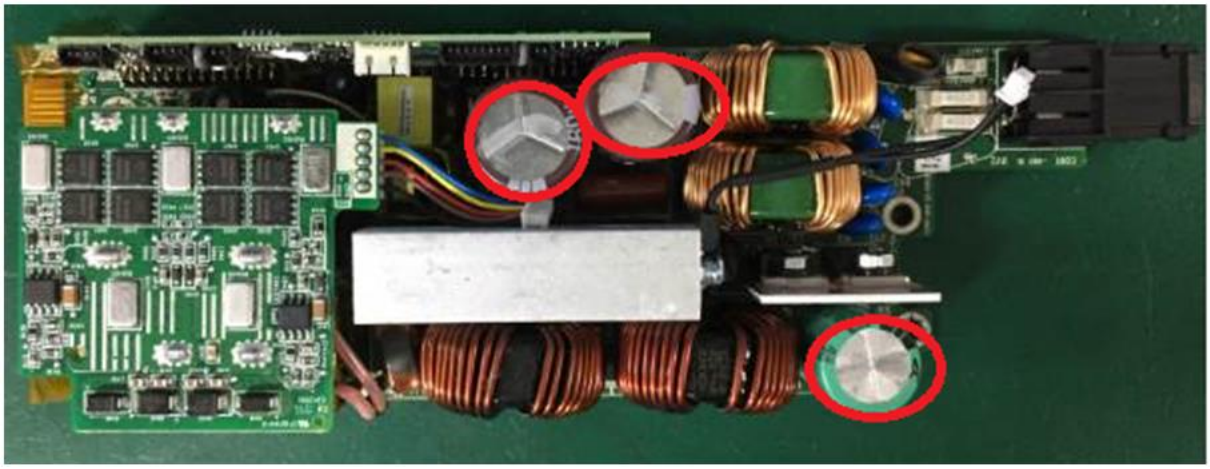
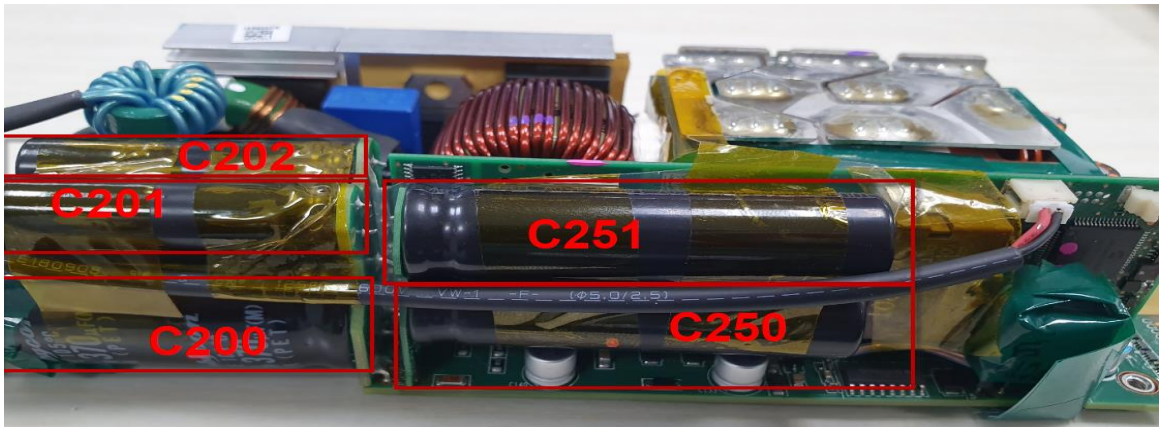
Remove Electrolytic Capacitor from power supply HSTNS-PF46-1.



Remove Electrolytic Capacitors (C201,202: 10mm*38.5mm, C200: 26mm*43mm , C250,251: 13mm*50mm) from power supply HSTNS-PR62.



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Remove Electrolytic Capacitor (C102: 30mm*30mm) from power supply HSTNS-PL62.

Remove Electrolytic Capacitor (C12:1.60mm*25mm, C328:18mm*30mm) from power supply HSTNS-PD70.

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